CORWIL
TECHNOLOGY CORPORATION

Flip Chip Assembly

Highlights | **Excellent Quality and Superior Service**

- SemiAutomatic Flipchip bonding
  - Ideal for prototype and small volumes
  - SEC860
- Automatic Flip Chip bonding
  - Production Volumes
  - Datacon2200apm
- Stud Bumping
- FCBGA
- Chip on Board
- CORWIL Standard or Customer Specified Underfills

CORWIL*'s latest acquisitions in equipment and process engineering developments make us your ideal vendor for assembly of Flip Chip devices. Flip Chip product capability includes Flip Chip in package (FCIP) such as FCBGA and Flip Chip on board (FCOB).*

- CORWIL can accommodate organic laminates or ceramic substrates and can assemble single or multiple Flip Chip and wire-bonded IC's in hybrids or multi-chip modules. Both digital and analog (including high frequency) devices are handled.
- Solder bumped dice can be bonded to substrates with accuracy as good as 5 microns.
- CORWIL can place gold stud bumps on your standard die (with aluminum pads) for quick-turn flip chip processing. No under bump metalization required. Stud bumped die will be thermosonically attached to your substrate. Underfill is optional with this process.
- CORWIL can bond bumped die sizes from 0.5mm x 0.5mm and up and die thickness from 0.10mm to 5.0mm.
- Dice can be supplied either as wafers or in waffle packs.
- The solder joints are reflowed in nitrogen ambient under tight temperature control. Solder reflow profiles are available for eutectic and also for lead-free solder.
- CORWIL's Flip Chip assembly process is highly flexible to accommodate your engineering needs. Customers may request water-soluble flux or no-clean flux materials. Additionally, specific underfill material can be requested and is applied with precision dispenser systems under tight process controls for voidless underfill processing.
- **CORWIL** has built its reputation providing customers with:
  excellent quality and superior service

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ISO 9001:2000
FM38103

DSCC QML Listed
(Qualified Manufacturers List)
MIL-STD-883 DSCC Suitability